

**Product Summary** (@ T<sub>A</sub> = +25°C)

V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F(MAX)</sub> (V)	I <sub>R(MAX)</sub> (μA)
50	5	0.52	300

**Features and Benefits**

- Low Leakage Current
- Soft, Fast Switching Capability
- +150°C Operating Junction Temperature
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative.**  
<https://www.diodes.com/quality/product-definitions/>

**Applications**

- SMPS
- AC-DC
- DC-DC Converter
- Freewheeling Diodes
  - Reverse Polarity Protection
  - Blocking Diodes

**Mechanical Data**

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish.) Solderable per MIL-STD-202, Method 208 (3)
- Polarity Indicator: Cathode Band
- Weight: 0.036 grams (Approximate)



SMAF



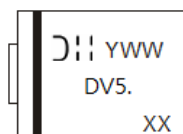
Device Symbol

**Ordering Information** (Note 4)

Part Number	Compliance	Case	Packaging
SDT5A50SAF-13	Commercial	SMAF	10,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information** (Note 5)



- DV5. = Product Type Marking Code
- J|| = Manufacturers' Marking
- YWW = Date Code Marking
- Y = Last Digit of Year (ex: 9 for 2019)
- WW = Week Code 01 to 52
- XX = Foundry and Assembly Site

Note: 5. Device has a cathode band (as shown) and may also have a cathode notch.

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	50	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>RM</sub>		
Average Rectified Output Current	I <sub>O</sub>	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	50	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction to Ambient (Note 6)	R <sub>θJA</sub>	51	°C/W
Thermal Resistance Junction to Case (Note 6)	R <sub>θJC</sub>	28	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V <sub>F</sub>	—	0.35	—	V	I <sub>F</sub> = 1.0A, T <sub>J</sub> = +25°C
		—	0.46	0.52		I <sub>F</sub> = 5.0A, T <sub>J</sub> = +25°C
		—	0.39	0.45		I <sub>F</sub> = 5.0A, T <sub>J</sub> = +125°C
Leakage Current (Note 7)	I <sub>R</sub>	—	35	300	μA mA mA	V <sub>R</sub> = 50V, T <sub>J</sub> = +25°C
		—	3	—		V <sub>R</sub> = 45V, T <sub>J</sub> = +100°C
		—	12	90		V <sub>R</sub> = 50V, T <sub>J</sub> = +125°C

Notes: 6. FR-4 substrate, 0.4"×0.5", 2oz, single-sided, PC boards with 0.2"×0.25" copper pad.  
 7. Short duration pulse test used to minimize self-heating effect.

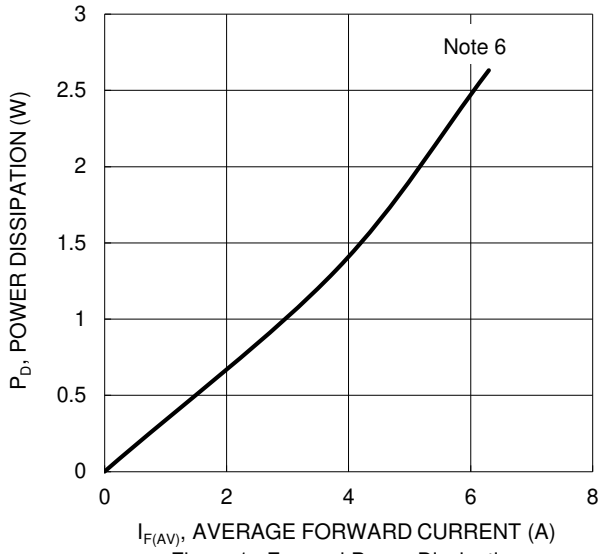


Figure 1. Forward Power Dissipation

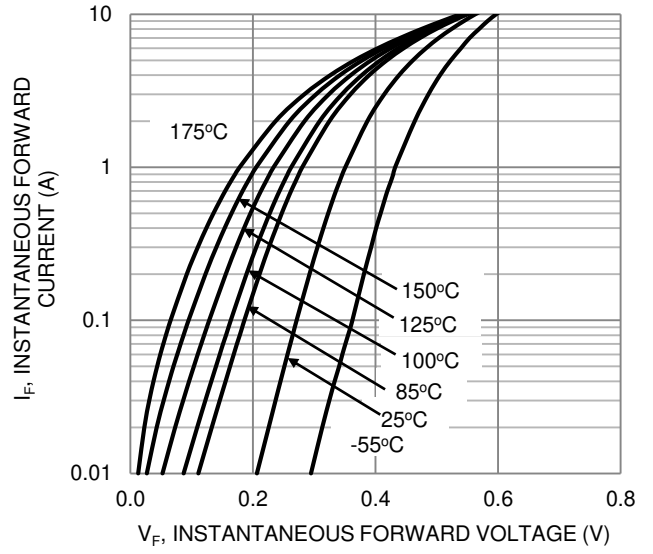


Figure 2. Typical Forward Characteristics

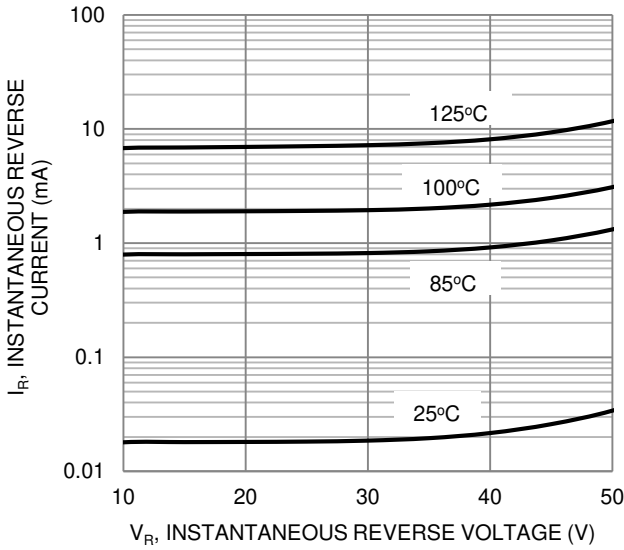


Figure 3. Typical Reverse Characteristics

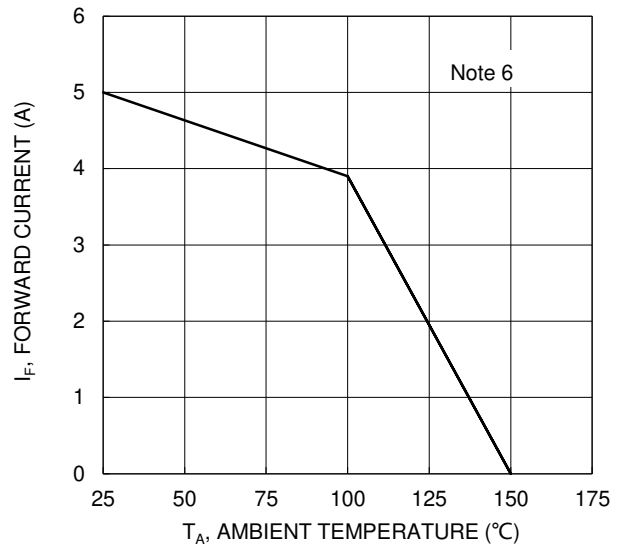
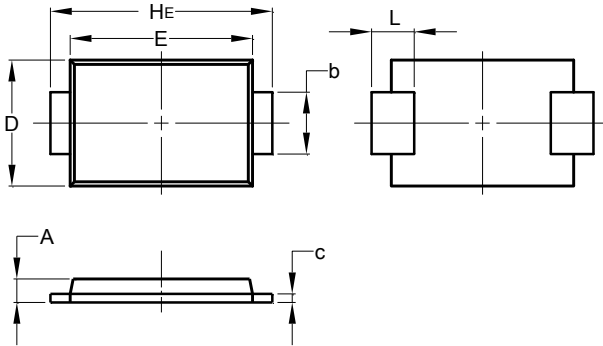


Figure 4. Forward Current Derating Curve

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF

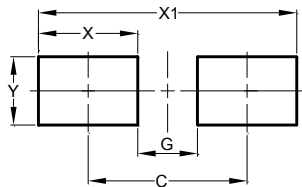


SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
HE	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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